

L Number	Hits	Search Text	DB	Time stamp
2	0	("Substrate and ((bevel or level or step or stepped or groove) near (line or pattern or metallization or metal or trace))").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 14:32
3	16220	Substrate and ((bevel or level or step or stepped or groove) near (line or pattern or metallization or metal or trace))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 15:52
4	6325	(Substrate and ((bevel or level or step or stepped or groove) near (line or pattern or metallization or metal or trace))) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 14:40
5	5967	(Substrate and ((bevel or level or step or stepped or groove) near (line or pattern or metallization or metal or trace))) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 13:35
6	2469	((Substrate and ((bevel or level or step or stepped or groove) near (line or pattern or metallization or metal or trace))) and 257/\$.ccls.) and ((step or stepped) near (line or pattern or metallization or metal or trace))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 13:38
7	2139	((Substrate and ((bevel or level or step or stepped or groove) near (line or pattern or metallization or metal or trace))) and 257/\$.ccls.) and ((step or stepped) near (line or pattern or metallization or metal or trace))) and (@ad<20010307)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 14:41
8	1595	((((Substrate and ((bevel or level or step or stepped or groove) near (line or pattern or metallization or metal or trace))) and 257/\$.ccls.) and ((step or stepped) near (line or pattern or metallization or metal or trace))) and (@ad<20010307)) and circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 13:41
9	0	("Substrate and (((thick and thin) or bevel or level or step or stepped or groove) near ((circuit adj line) or pattern or metallization or metal or trace))").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 14:33
10	14162	Substrate and (((thick and thin) or bevel or level or step or stepped or groove) near ((circuit adj line) or pattern or metallization or metal or trace))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 14:40
11	1862	(Substrate and (((thick and thin) or bevel or level or step or stepped or groove) near ((circuit adj line) or pattern or metallization or metal or trace))) and (chip or die) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 14:40
12	1476	((Substrate and (((thick and thin) or bevel or level or step or stepped or groove) near ((circuit adj line) or pattern or metallization or metal or trace))) and (chip or die) and pad) and (@ad<20010307)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 14:45

13	1167	((Substrate and (((thick and thin) or bevel or level or step or stepped or groove) near ((circuit adj line) or pattern or metallization or metal or trace))) and (chip or die) and pad) and (@ad<20010307)) not (((((Substrate and ((bevel or level or step or stepped or groove) near (line or pattern or metallization or metal or trace))) and 257/\$.ccls.) and ((step or stepped) near (line or pattern or metallization or metal or trace))) and (@ad<20010307)) and circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 14:51
14	0	6183267.URPN.	USPAT	2003/07/30 15:18
15	12	("3842189" "5172050" "5476211" "5510721" "5601740" "5613861" "5632631" "5665648" "5772451" "5773780" "5806181" "5926951").PN.	USPAT	2003/07/30 15:18
16	0	99544.URPN.	USPAT	2003/07/30 15:52
17	0	99544.URPN.	USPAT	2003/07/30 15:52
18	0	99544.URPN.	USPAT	2003/07/30 15:52
19	16	(Substrate and (((thick and thin) or bevel or level or step or stepped or groove) near ((circuit adj line) or pattern or metallization or metal or trace))) and 257/692.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/30 15:53

L Number	Hits	Search Text	DB	Time stamp
-	0	"409045691"	JPO; DERWENT	2003/06/30 05:30
-	0	"9045691"	JPO; DERWENT	2003/06/30 05:43
-	87	((interconnect and barrier and (copper or cu)) with trench) and (@ad<19990902)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/30 05:52
-	42	((interconnect and barrier and (copper or cu)) with trench) and (@ad<19990902)) and ((planarize or cmp) with (copper or cu))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/30 05:53